PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Junjie J. Sang	09/25/2012
Dalip K. Kohli	09/24/2012
Kunal G. Shah	10/05/2012

RECEIVING PARTY DATA

Name:	Cytec Technology Corp.
Street Address:	300 Delaware Avenue
City:	Wilmington
State/Country:	DELAWARE
Postal Code:	19801

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13652724

CH $40.00 13652724

CORRESPONDENCE DATA

Fax Number: 2033212971
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 203-321-2916
Email: stamfordpatent@cytec.com
Correspondent Name: CYTEC INDUSTRIES INC.
Address Line 1: 1937 WEST MAIN STREET
Address Line 2: P.O. BOX 60
Address Line 4: STAMFORD, CONNECTICUT 06904-0060

ATTORNEY DOCKET NUMBER:	10042S-US-NP
NAME OF SUBMITTER:	Thi D. Dang
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 6
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DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention	**STRUCTURAL ADHESIVE AND BONDING APPLICATION THEREOF**

As the below named inventor, I hereby declare that:

This declaration is directed to:
(check one) [X] The attached application, or
[ ] United States application or PCT international application number ____________ filed on ____________.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

For good and valuable consideration, the receipt of which is hereby acknowledged, I hereby assign, sell and transfer to **CYTEC TECHNOLOGY CORP., with offices at 300 Delaware Avenue, Wilmington, Delaware 19801,** (hereinafter referred to as the ASSIGNEE) its successors and assigns: (1) my entire right, title and interest for the United States and in all foreign countries, in and to the above-identified application, including any renewals, revivals, reissues, reexaminations, extensions, continuations and divisions thereof and any substitute applications therefor; (2) the full and complete right to file patent applications in the name of the ASSIGNEE, its designee, or in my name at the ASSIGNEE's, or its designee's election, on said invention in all countries of the world; (3) the entire right, title and interest in and to any Letters Patent which may issue thereon in the United States or in any country, and any renewals, revivals, reissues, reexaminations and extensions thereof, and any patents of confirmation, registration and importation of the same; and (4) the entire right, title and interest in all Convention and Treaty Rights of all kinds thereon, including without limitation all rights of priority in any country of the world, in and to the above-identified application.

I hereby authorize and request the competent authorities to grant and to issue any and all Letters Patent in the United States and throughout the world to the ASSIGNEE of the entire right, title and interest therein, as fully and entirely as the same would have been held and enjoyed by me had this assignment, sale and transfer not been made.

I further agree at any time to execute and to deliver upon request of the ASSIGNEE additional documents, if any, as are necessary or desirable to secure patent protection on said invention throughout all countries of the world, and otherwise to do that is necessary to give full effect to and to perfect the rights of the ASSIGNEE under this Assignment, including the execution, delivery and procurement of any and all further documents evidencing this assignment, transfer and sale as may be necessary or desirable.

I hereby covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention as may be known and accessible to me, and will testify as to the same in any legal proceeding related thereto, and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to obtain and enforce proper patent protection for said invention in the United States and in any and all foreign countries.

I further covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

I hereby grant the attorneys of record the power to correct typographical errors and to insert into this document any further identification that may be necessary or desirable.

LEGAL NAME OF INVENTOR

Inventor: **JUNJIE JEFFREY SANG**

Inventor's Signature: Junjie Sang	Date: 9/25/2012

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LEGAL NAME OF INVENTOR

Inventor: **DALIP KUMAR KOHLI**

Inventor's Signature: Dalip K. Kohli	Date: 9/24/2012

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LEGAL NAME OF INVENTOR

Inventor: **KUNAL GAURANG SHAH**

Inventor's Signature:	Date: OCT 5th, 2012